



Continuous innovation and improvement
All employees pursue excellence

2023 Third Quarter Investor Conference

Stock symbol : 6207
2023/12/19

LASER TEK TAIWAN CO., LTD.

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Agenda

(一) Company Overview

(二) 2023 3Q Operating Performance

(三) Laser Product R&D and Industrial Application



(一)

Company Overview



全球奇聞聲譽品牌，聚焦核心光電技術，拓展利基新市場，提供完整服務方案



公司簡介

Date of Establishment : Sep 9th, 1988

Capital : 796 Million NT Dollars

President : Gary Cheng

Employees : Over 300employees Worldwide

Worldwide Operation : Taiwan, China, Singapore

Product : Surface Mount Device Packaging Materials

Laser Equipment

Surface Mounted Technology Equipment

Energy Saving

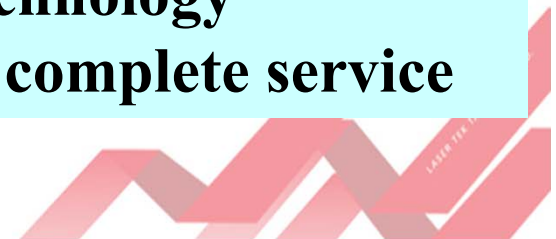
Germagic Epidemic Prevention Products

Corporate Headquarter :

No.248-39, Shin-Sheng Rd., Chien-Zhen District, Kaohsiung, Taiwan, R.O.C.

Global layout, focus on core optoelectronic technology

Expand Niche Blue Ocean market, providing complete service



Business Location

**Prolaser
(KunShan,
China)**



**Warehouse
(DongGuan
, China)**



**Laser Tek
(Singapore)**



HsinChu Branch



LaserTek Headquarter

Kaohsiung Hsin Sheng Building



Products



設備事業 (Laser & Metrology Equipments)

LASER Equipment

METROLOGY Equipment



SMD捲裝材料事業 (Surface Mount Device Packaging Materials)

PCT Products

ECT Products



Energy Saving Devices / GERMAGIC防疫產品

LED Products

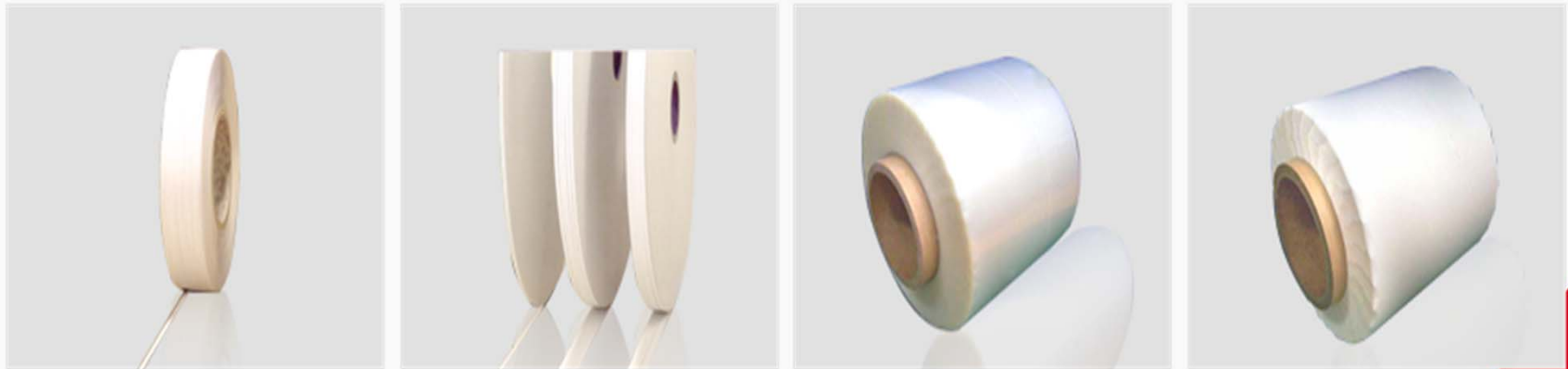
Air Purifier

GERMAGIC Epidemic Prevention Products



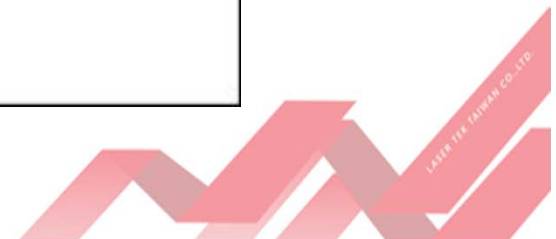
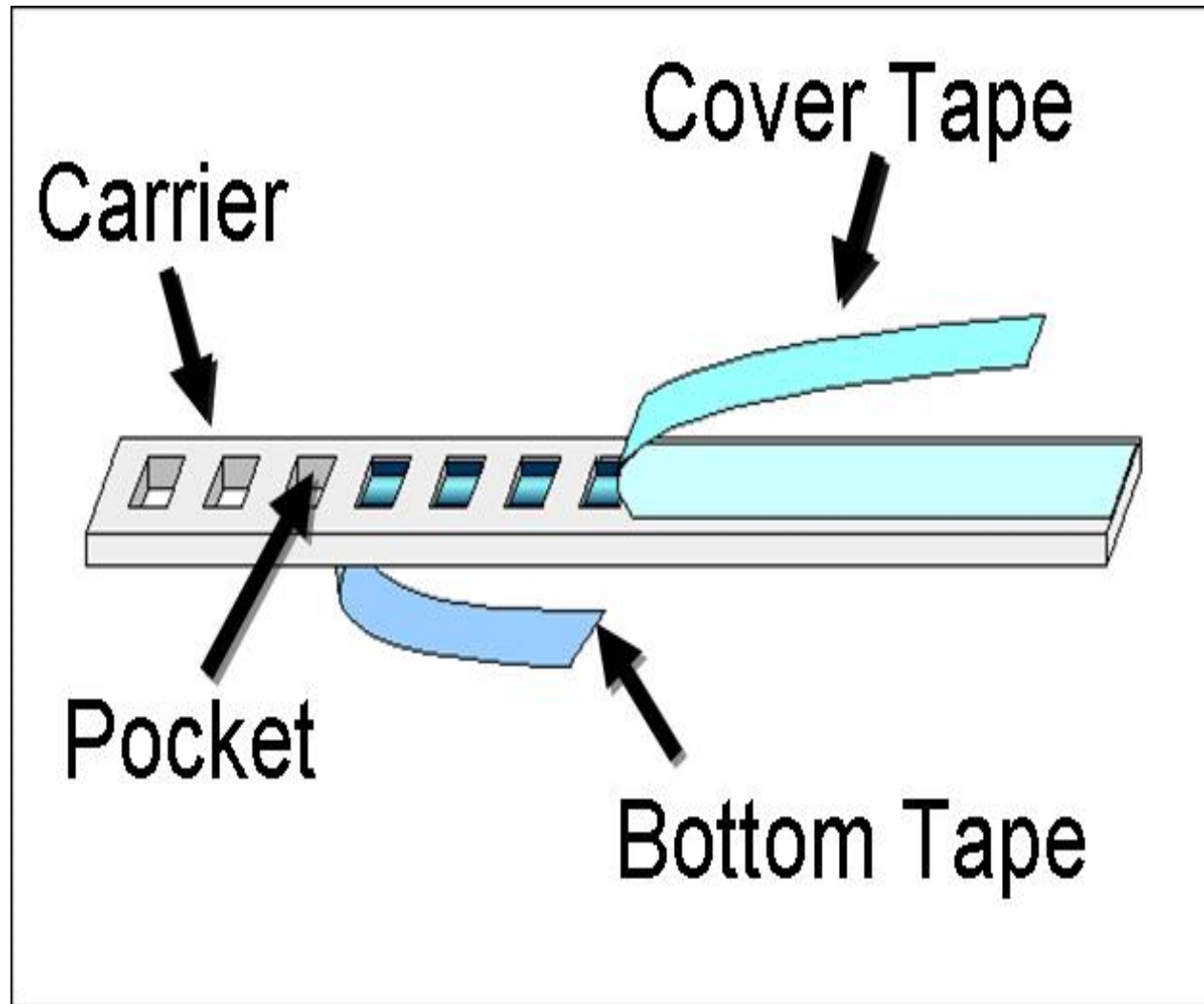
SMD捲裝材料事業 (Surface Mount Device Packaging Materials)

SMD-PCT Products



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SMD Products The structure of the conveyable tape



SMD PCT Customers

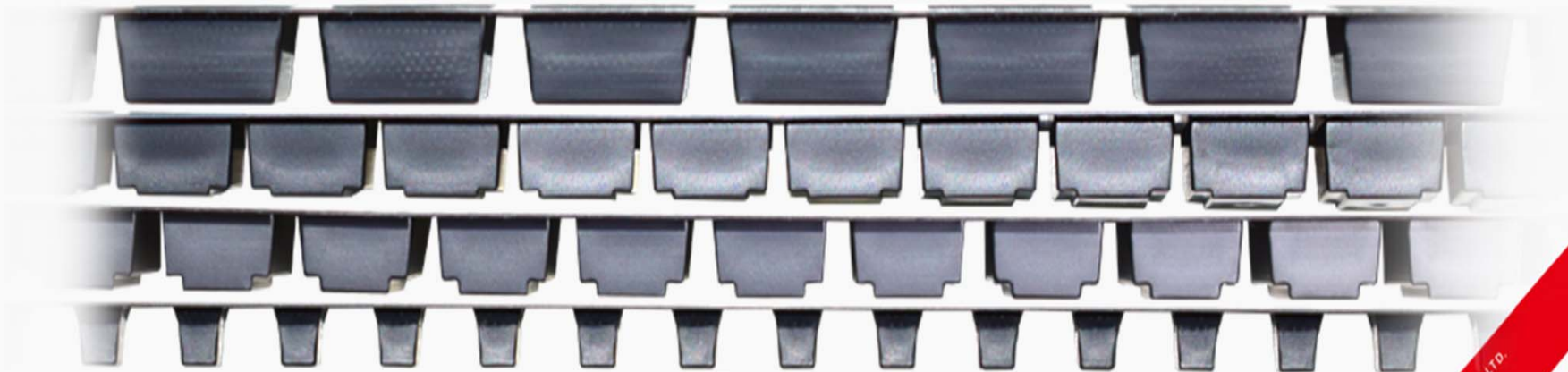


全球第一局器品牌，聚焦核心光電技術，拓展利基藍海市場，提供完整服務方案



SMD捲裝材料事業 (Surface Mount Device Packaging Materials)

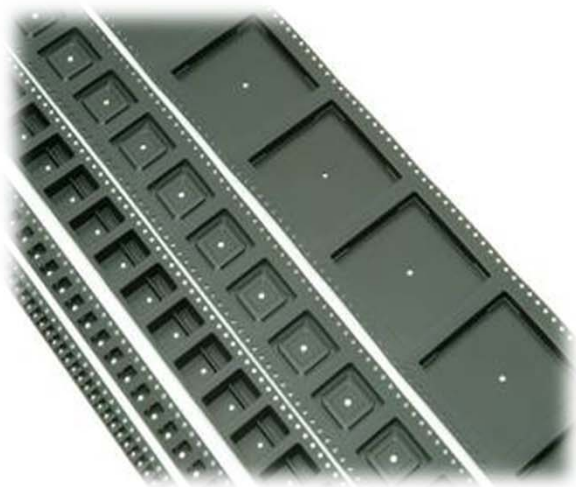
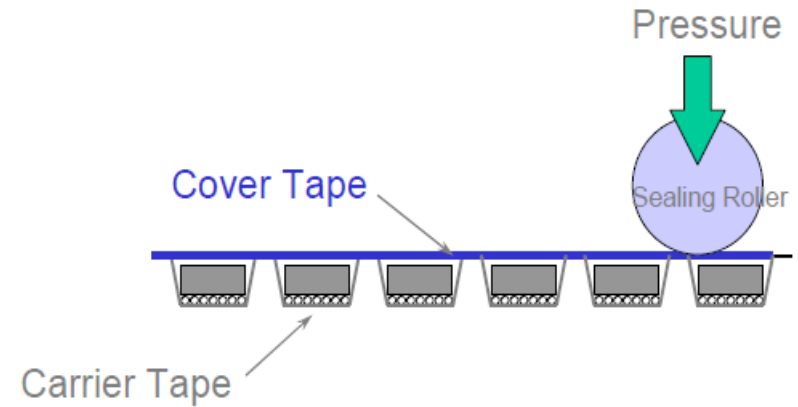
SMD-ECT **Embossed Carrier Tape**



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Embossed Carrier Tape

- Carrier Tape : Packaging tapes for IC semiconductors, electronic passive components, LED products, etc.
- The main materials are PC, PS... and other plastic raw materials.



LASERTEK

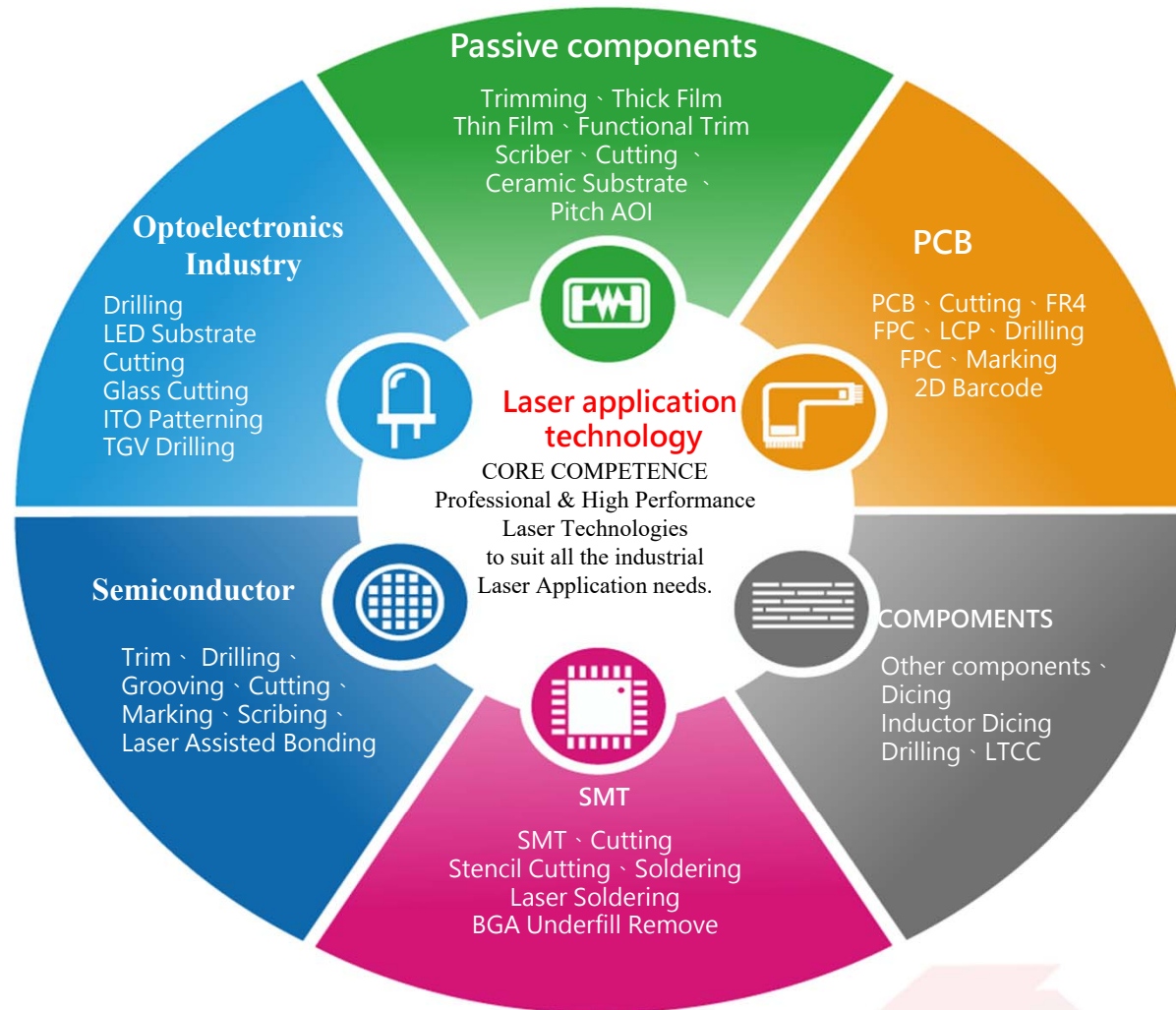
封装奇聞品牌 · 聚焦核心光電技術 · 拓展利基新市場 · 提供光電服務方案



SMD ECT Customers



Laser & Metrology Equipments





2023 3Q Operating Performance



持续提升產品種類，聚焦核心光電技術，拓展利基斷新市場，提供完整服務方案



Statements of Comprehensive Income

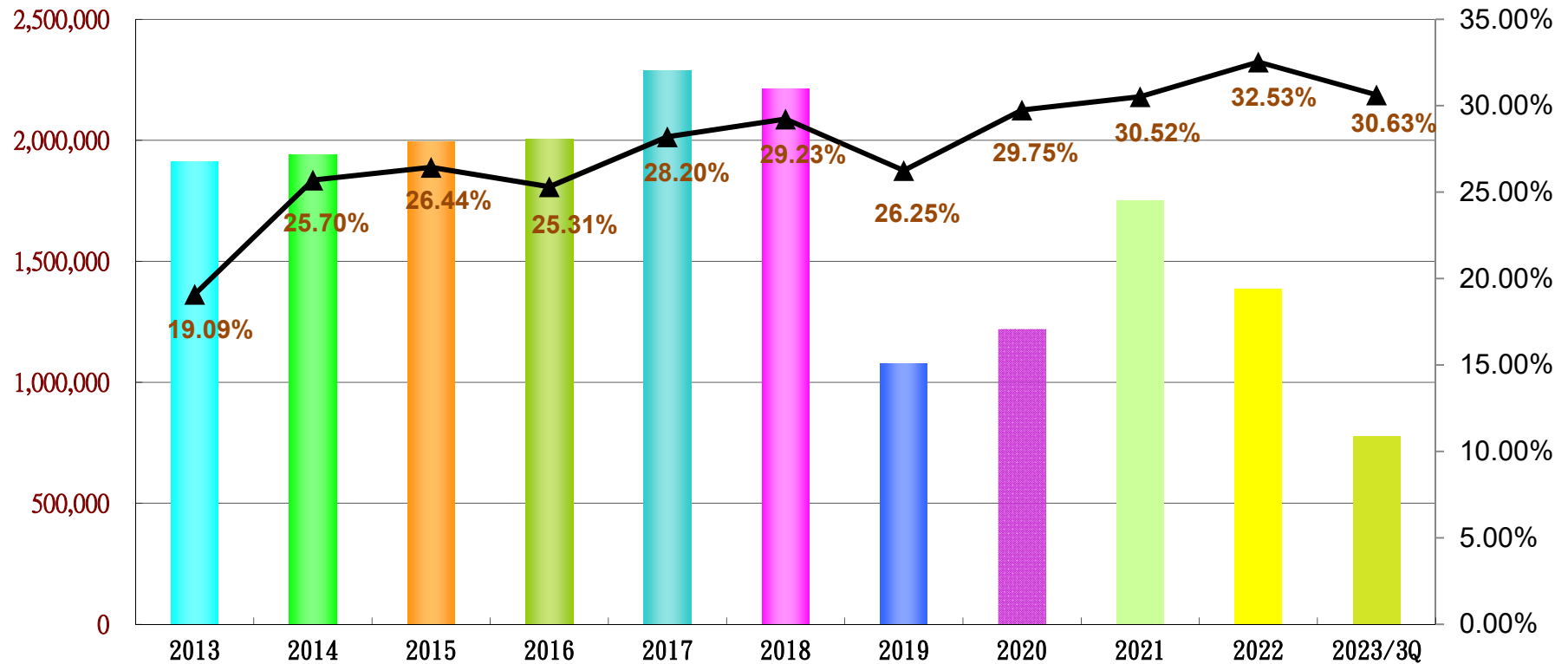
Units : NT\$ Thousand;%

| Items | 2023 3Q | 2022 3Q | 2023/3Q Over 2022/3Q | 2023/Q3 (Single Quarter) | 2022/Q3 (Single Quarter) | 2023/Q3 Over 2022/Q3 (Single Quarter) |
|--|---------|-----------|----------------------------|--------------------------------|--------------------------------|---|
| Operating Revenue | 776,739 | 1,046,591 | -25.78% | 332,983 | 353,847 | -5.90% |
| Gross Margin | 30.63% | 31.51% | -2.79% | 29.56% | 30.83% | -4.12% |
| Operating Expenses | 216,652 | 221,762 | -2.30% | 80,457 | 80,400 | 0.07% |
| Operating Margin(Loss) | 21,266 | 108,020 | -80.31% | 17,957 | 28,681 | -37.39% |
| Operating profit margin | 2.74% | 10.32% | -73.45% | 5.39% | 8.11% | -33.54% |
| Non-Operating items | 122,305 | 90,399 | 35.29% | 37,983 | 42,913 | -11.49% |
| Net income(Loss) to Shareholders of the Parent Company | 115,371 | 158,034 | -27.00% | 44,485 | 55,941 | -20.48% |
| Net profit margin | 14.85% | 15.10% | -1.66% | 13.36% | 15.81% | -15.50% |
| EPS(NT Dollar) | 1.45 | 1.88 | -22.87% | 0.56 | 0.67 | -16.42% |
| ROE | 6.41% | 9.62% | -33.37% | 2.38% | 3.31% | -28.10% |

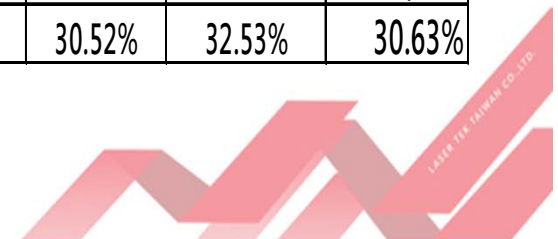


Operating revenue / Gross margin

Units : NT\$ Thousand;%

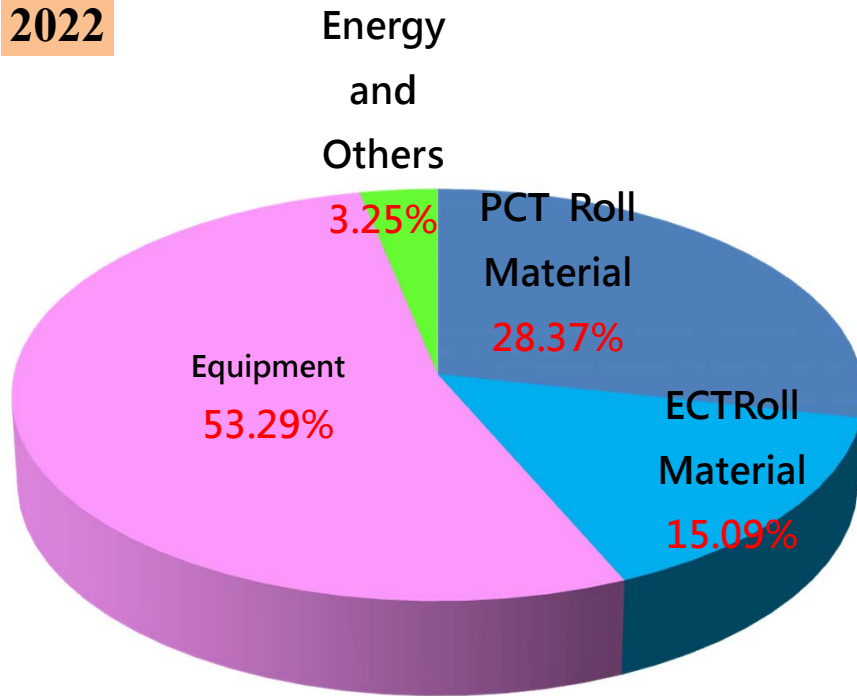


| Items | 2013 | 2014 | 2015 | 2016 | 2017 | 2018 | 2019 | 2020 | 2021 | 2022 | 2023/3Q |
|--------------|-----------|-----------|-----------|-----------|-----------|-----------|-----------|-----------|-----------|-----------|---------|
| Revenue | 1,913,318 | 1,941,943 | 1,995,668 | 2,004,536 | 2,287,415 | 2,211,070 | 1,078,330 | 1,221,008 | 1,751,466 | 1,386,770 | 776,739 |
| Gross Margin | 19.09% | 25.70% | 26.44% | 25.31% | 28.20% | 29.23% | 26.25% | 29.75% | 30.52% | 32.53% | 30.63% |

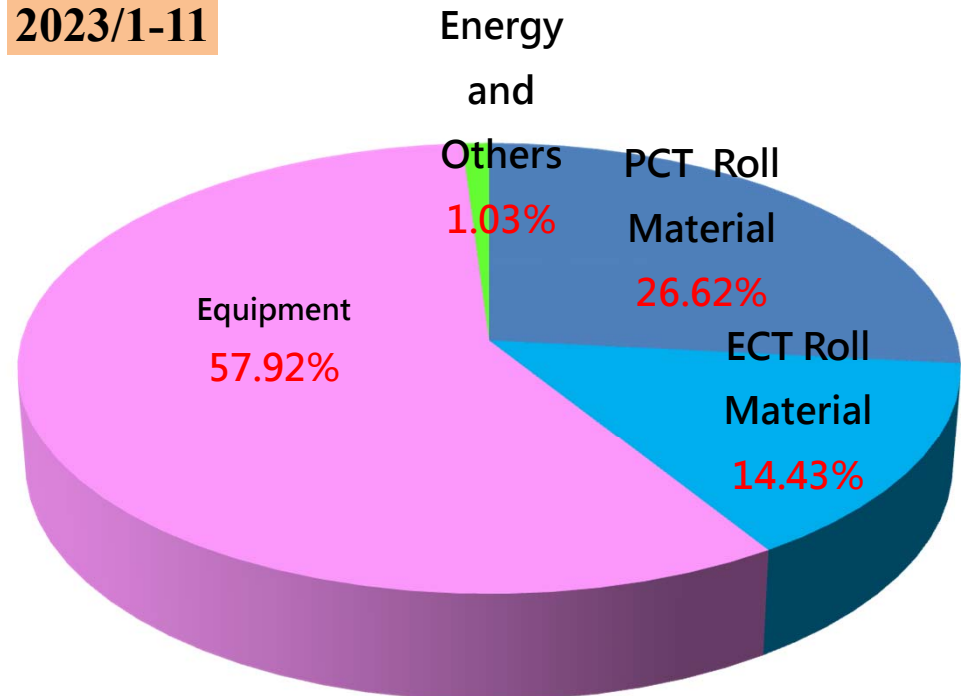


Products revenue share %

2022



2023/1-11

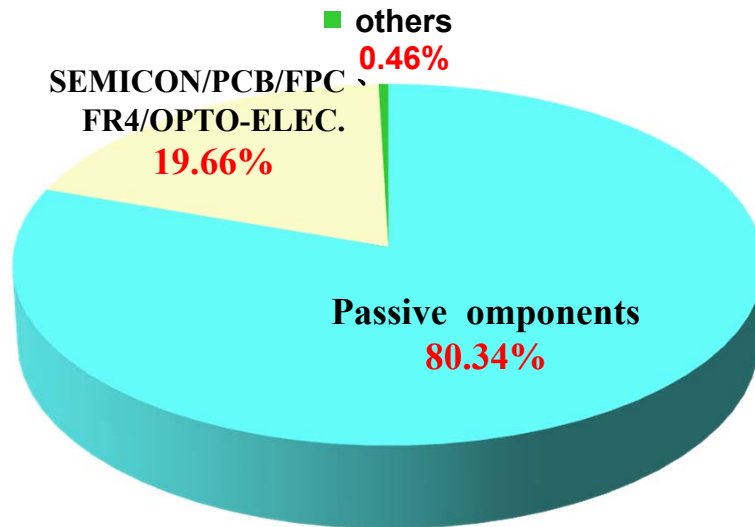


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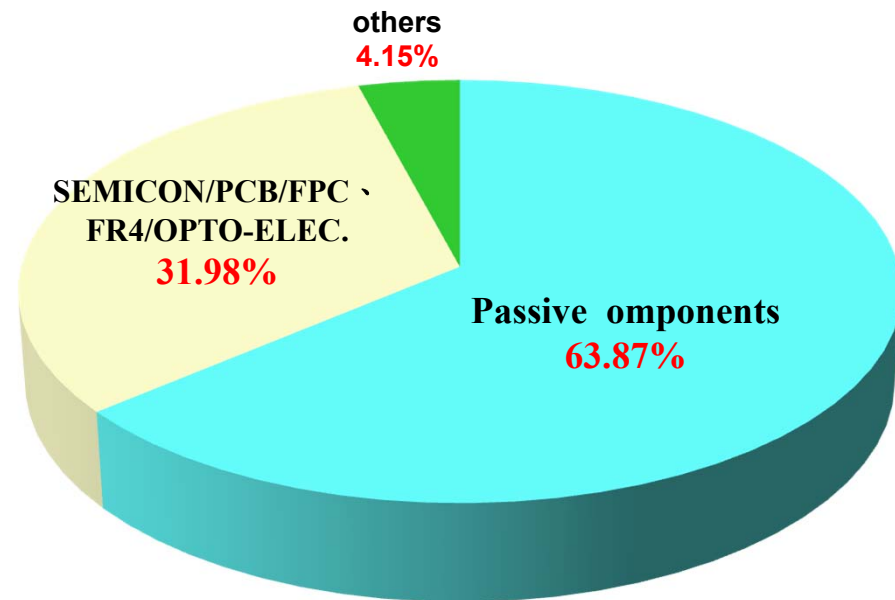


Industry revenue percentage of products

2021

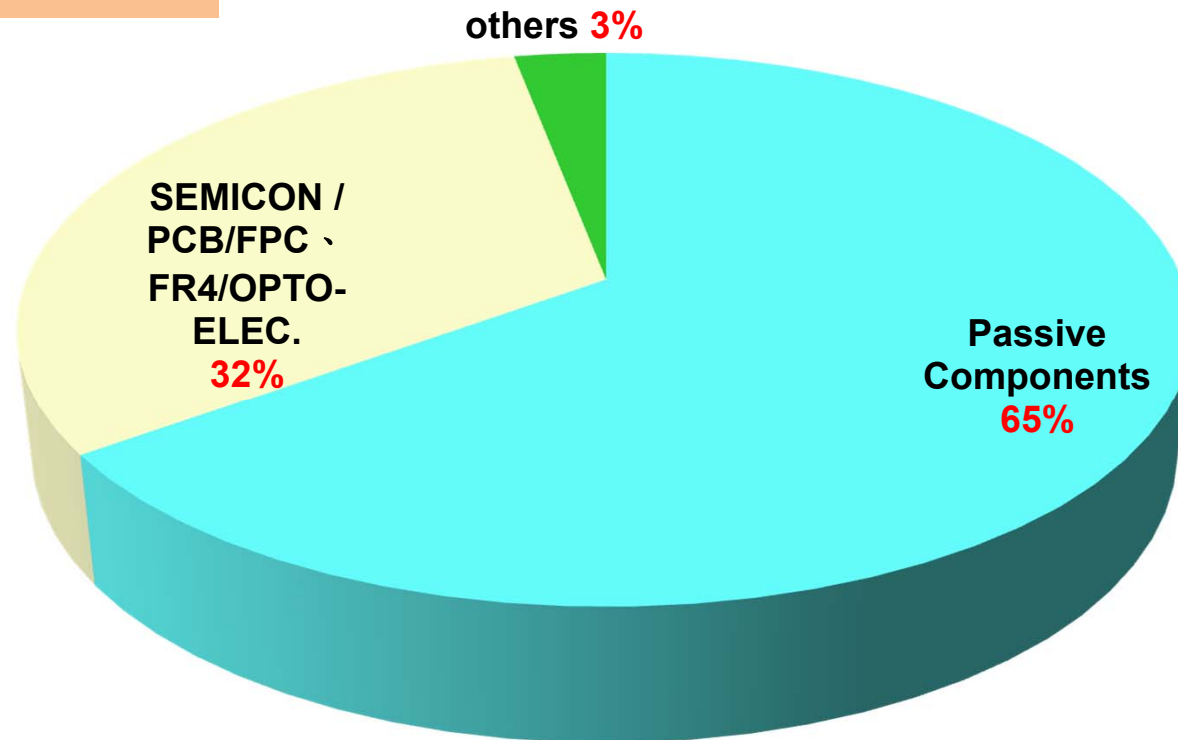


2022

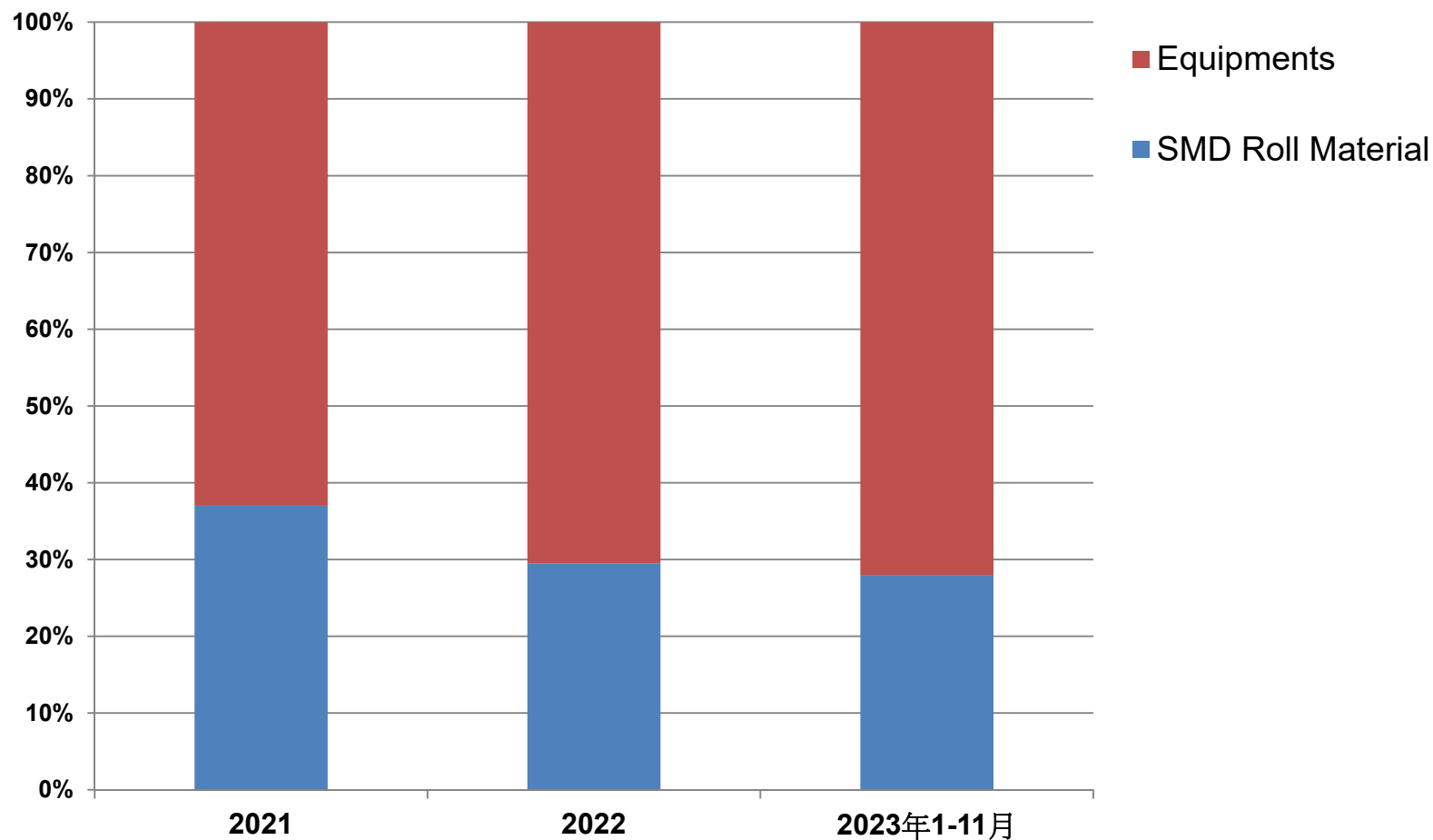


Industry revenue percentage of products

2023/1-11



Gross profit of the company's product categories



持續研開發新產品，聚焦核心光電技術，拓展利基新市場，提供完整服務方案





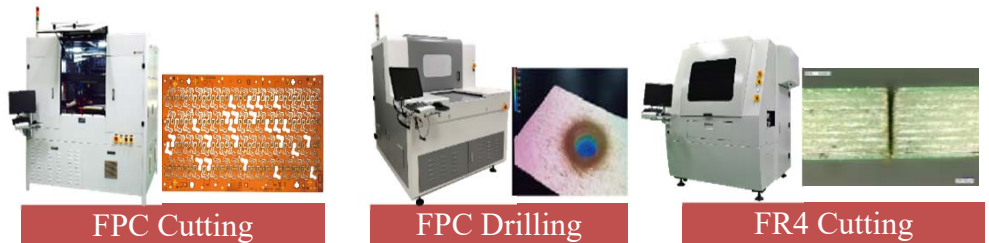
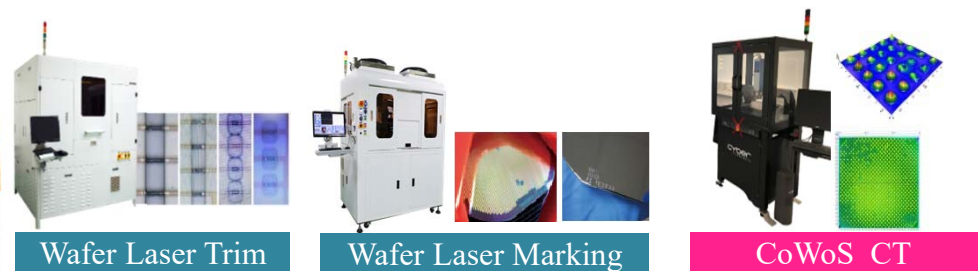
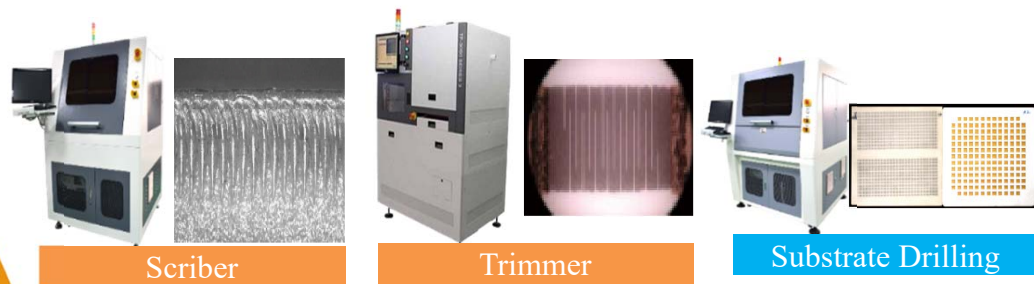
Laser Product R&D and Industrial Application



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Laser Core Competitiveness & Territory



Lasertek Products

SEMI



Wafer trim



Wafer marking



Wafer grooving

Substrate



FR4 cutting



substrate drilling



FPC cutting

Passive components



functional trim



Thin film trim



Tantalum trim

AI application



AI+AOI
Defect
inspection



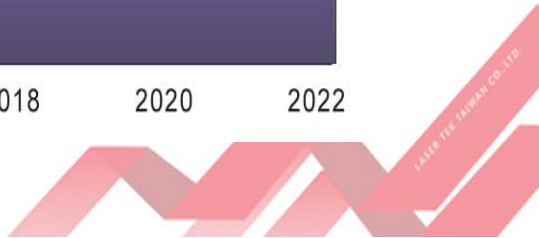
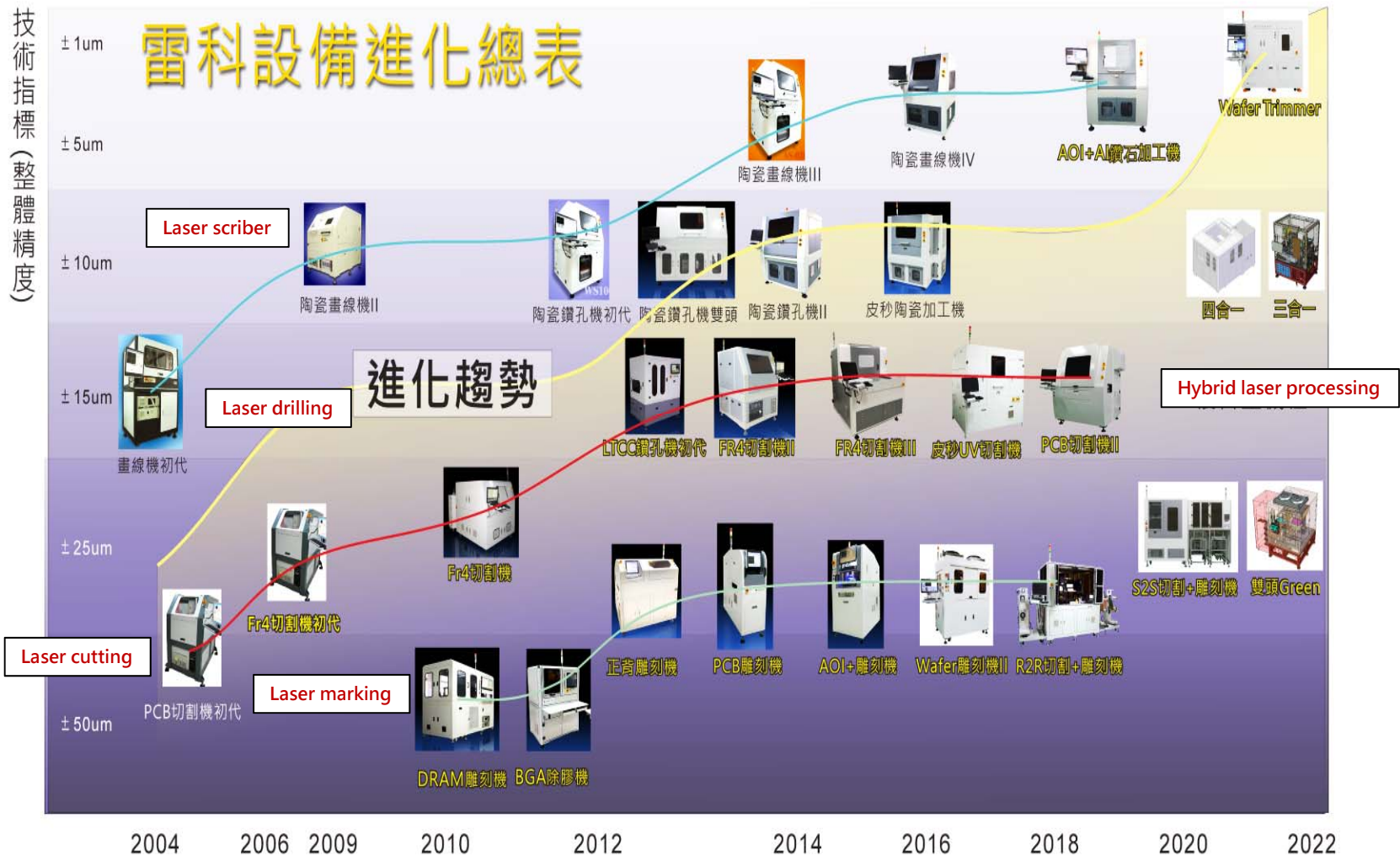
AI
Diamond
cutting
machine



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Lasertek R&D Roadmap



Four Application Field

SEMI



- Wafer trim
- CoWoS
- LAB
- SIC cutting
- Glass wafer

Substrate



- FR4 automotive electronics
- RF high frequency heat dissipation carrier board
- LCP 5G high frequency FPC
- Quantum computer FPC

Passive components



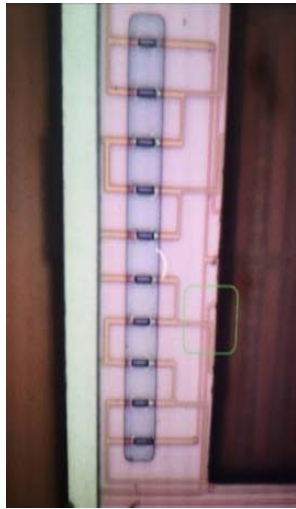
- Thick film
- Thin film (High precision)
- Functional trim
- Tantalum trim

AI application



- AI Defect inspection
- AI Diamond cutting

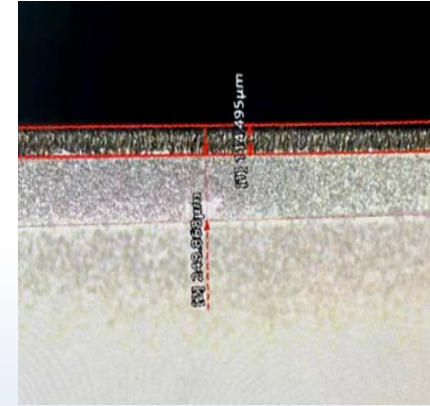
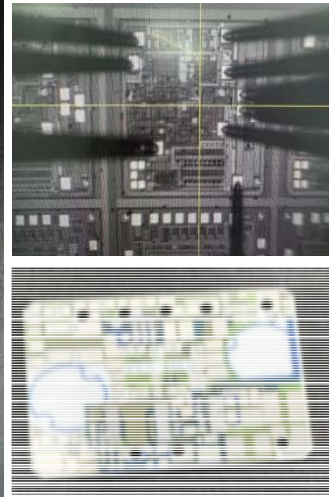
➤ Semiconductor Field Wafer / SIC / Glass Wafer application



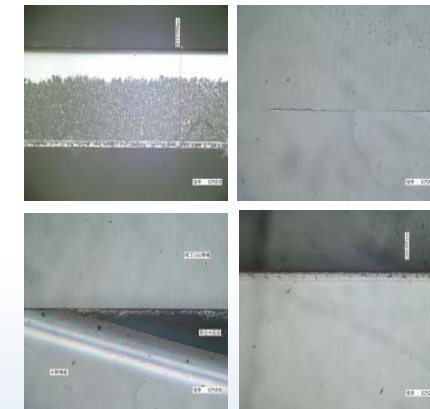
Power management IC
 1um overall processing accuracy
 1%rms energy stability



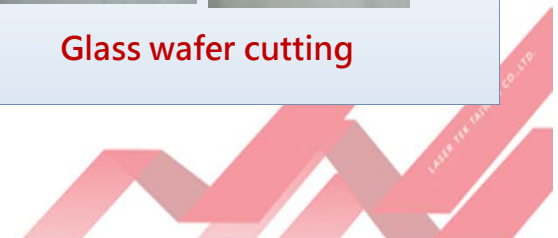
Instrument amplification IC
 Film thickness <1um trimming



SIC cutting



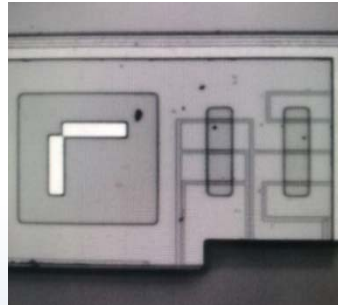
Glass wafer cutting



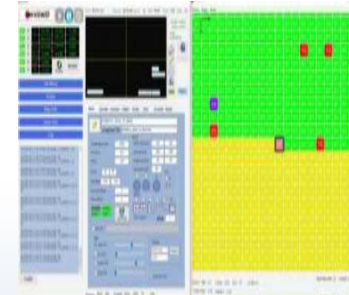
Core Technology Wafer Laser Trim



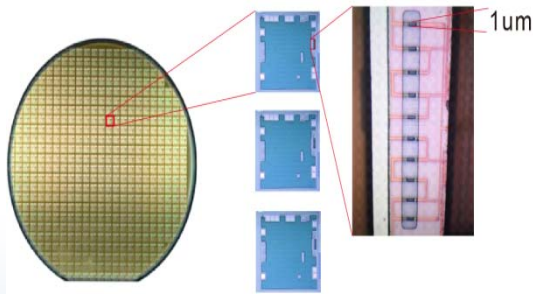
1uJ high-precision laser power compensation technology



Laser coaxial vision, resolution <1um



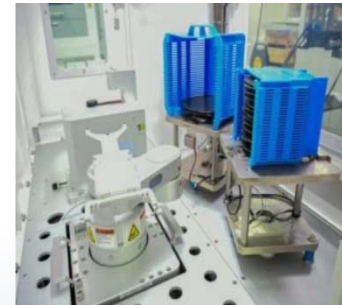
Customized mapping program to support multi die machining.



1um high-precision processing



External electrical instrumentation, supports more than 20 types of instrumentation



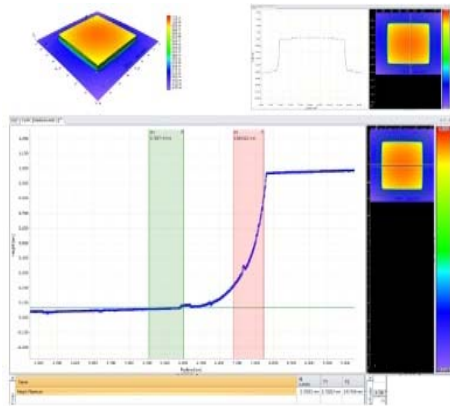
High-precision robot supports 4-8 inches



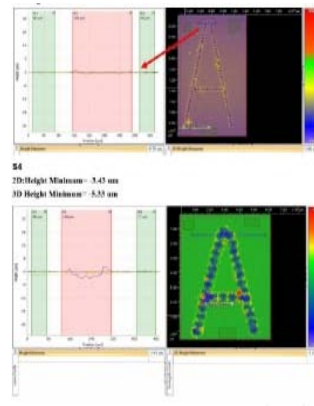


Semiconductor Field

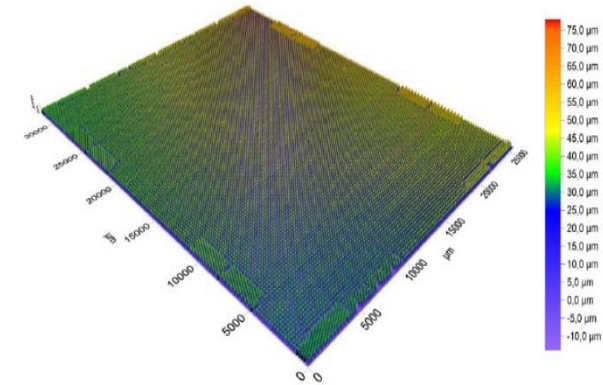
CoWoS Package Measurement



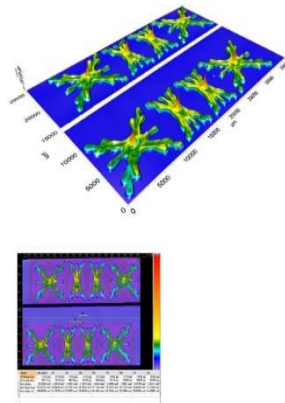
▲ UNDER-FILL GLUE FILLET HEIGHT



▲ LASER SCRIBING

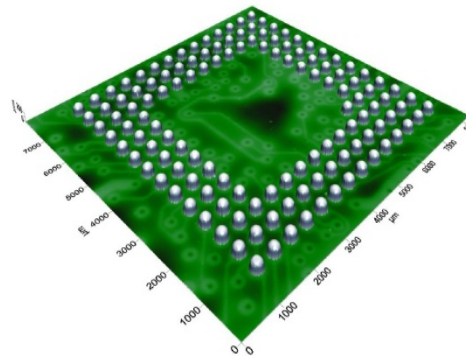


▲ C4 bump height ,diameter & warpage measurement (substrate surface side) by L-CHR

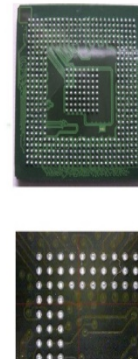


▲ SOLDER DISPENSED

Surface image of a Micro BGA



▲ HEIGHT, COPLANARITY –BGA SOLDER BUMPS



- CTWL200D
- CT350T
- CT450T
- CT600T (TTV)



- CT350
- CT450
- CT600



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持續創新改善 全員追求卓越

感謝您的蒞臨

Thank you for coming here today.

LASER TEK TAIWAN CO., LTD.